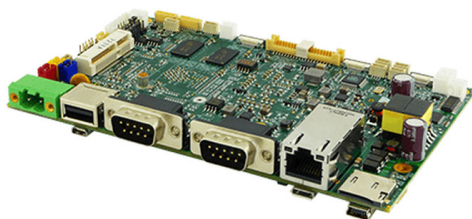


FA30 NXP i.MX6 Dual Core Industrial ARM SBC

Manufacturer part number: FA30 | Embedded Board



Explore Winmate FA30, an industrial embedded board featuring NXP i.MX6, 3.5-inch form factor for OEM equipment design and embedded control.

System Specification	
Processor	NXP i.MX6 Dual Core, 1.0GHz
Memory	1GB (Default), 2GB (Optional)
Storage	eMMC: Onboard 16 GB (Default), eMMC: Onboard 32 GB (Optional)
Operating System	Linux Ubuntu 18.04 (Optional), Android 6.0 (Optional), Debian 7.0 (Optional), Linux 4.1.15 QT 5.5 (Optional)
WLAN	Support (Optional)
BT	Support (Optional)
IO Ports	
USB Port	1 x Console Port (Mini USB), 1 x USB OTG (Micro USB), 1 x USB2.0 (Type-A)
Serial Port	1 x RS232/422/485 (Default RS232)
LAN	1 x LAN RJ45 Connector with PoE(PD, 802.3 at)
Video	1 x Micro HDMI (Optional)
SD Card Slot	1 x Micro SD card slot
CANBUS	1 x CANBUS, D-sub9
Power Input	1 x 12V DC, 2-Pin Terminal Block
Internal IO Ports	
Power output	1 x 2pin(1x2) blue wafer for 3.3V DC out, 1 x 2pin(1x2) red wafer for 5V DC out , 1 x 2pin(1x2) yellow wafer for 12V DC out
USB	5 x 4pin(1x4) for USB 2.0
UART	2 x 8pin(1x8) for UART, 1 x 6pin(1x6) for debug
Display	1 x 40pin DF13 connector for LVDS
Backlight	1 x 7pin(1x7) for panel backlight, 1 x 2pin(1x2) for backlight
DIDO	1 x 10pin(2x5) for Digital input/output
VR	1 x 3pin(1x3) for Backlight control VR
Speaker	2 x 2pin(1x2) for Speaker
Backup battery	1 x 2pin(1x2) for RTC battery
Audio	1 x 2pin(1x2) for Microphone
Reset	1 x 4pin(1x4) for Reset

CAN2	1 x 4pin(1x4) for CAN2
I2C	1 x 12pin FPC connector for NFC, 1 x 10pin FPC connector for Touch
Certification	
Certification	CE, FCC
Mechanical	
Dimension	146 x 102 mm
Environment	
Operating Humidity	30% to 90% RH, Non-Condensing
Operating Temperature	-20 deg C to 60 deg C
Storage Temperature	-25 deg C to 65 deg C
Power	
Power Rating	12V DC
Adapter	12V 50W
POE	PoE (PD): follows IEEE 802.3at (25 W)